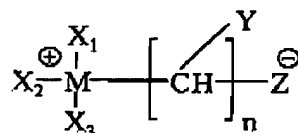


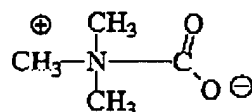
Claims:

1. (Currently amended) An aqueous composition useful for polishing silica and silicon nitride on a semiconductor wafer comprising by weight percent 0.01 to 5 zwitterionic compound, 0.01 to 5 carboxylic acid polymer, 0.02 to 6 ~~abrasive~~ ceria, 0 to 5 cationic compound and balance water, the zwitterionic compound having the following structure:



wherein n is an integer, Y comprises hydrogen or an alkyl group, Z comprises carboxyl, sulfate or oxygen, M comprises nitrogen, phosphorus or a sulfur atom, and X₁, X₂ and X₃ independently comprise substituents selected from the group comprising, hydrogen, an alkyl group and an aryl group.

2. (Original) The composition of claim 1 wherein the zwitterionic compound has the following structure:



3. (Original) The composition of claim 1 wherein the cationic compound is selected from the group comprising: alkyl amines, aryl amines, quaternary ammonium compounds and alcohol amines.

4. (Canceled)

5. (Currently Amended) The composition of claim [[4]] 1 wherein the ceria has an average particle size of between 50-200 nm.

6. (Original) The composition of claim 1 wherein the aqueous composition has a pH of 4 to 9.

7. (Currently amended) An aqueous composition ~~useful~~ for polishing silica and silicon nitride on a semiconductor wafer comprising by weight percent 0.01 to 5 N,N,N-trimethylammonioacetate, 0.01 to 5 polyacrylic acid polymer, 0.02 to 6 ceria, 0 to 5 cationic compound and balance water, wherein the aqueous composition has a pH of 4 to 9.

8 - 10. (Canceled)